

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSB280N15NZ3 G	**Issued**	02. June 2021
MA#	MA000845558		
Package	MG-WDSON-2-9	**Weight***	83.57 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.059	4.86	4.86	48567	48567
leadframe	non noble metal	copper	7440-50-8	74.415	89.04	89.04	890422	890422
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2527	
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10051	12578
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2527	2527
solder	non noble metal	copper	7440-50-8	0.011	0.01		131	
	noble metal	silver	7440-22-4	0.066	0.08		788	
	non noble metal	tin	7440-31-5	2.119	2.54	2.63	25350	26269
glue	plastics	acrylic resin	-	0.184	0.22		2201	
	noble metal	silver	7440-22-4	1.130	1.35	1.57	13519	15720
passivation	plastics	epoxy resin	-	0.327	0.39	0.39	3917	3917
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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